CLAIMS

[Claim 1]

An index system polishing apparatus which includes a polishing head for holding a wafer, a plurality of turn tables to which polishing pads for polishing the wafer are attached, and a loading/unloading stage for loading the wafer to the polishing head or unloading the wafer from the polishing head, and which polishes the wafer while switching the turn tables to be used for polishing the wafer held at the polishing head by causing the polishing head to perform rotation movement,

the polishing apparatus comprising a turn table upward and downward movement mechanism which allows the turn tables to move upward and downward,

wherein the polishing apparatus has a polishing head upward and downward movement mechanism which causes the polishing head to move upward and downward with a stroke width of 20 mm or less,

and rotation movement of the polishing head and upward and downward movement of the turn tables and the polishing head can be performed in parallel.

[Claim 2]

The polishing apparatus according to claim 1,

wherein the polishing apparatus has a dressing mechanism at a position where the dressing mechanism does not interfere with a trajectory on which the polishing head performs rotation movement.

[Claim 3]

The polishing apparatus according to claim 2,

wherein the turn table upward and downward

movement mechanism adjusts height of the turn tables according to abrasion of the polishing pads when dressing of the polishing pads is performed by the dressing mechanism.

[Claim 4]

A wafer polishing method using the polishing apparatus according to any one of claims 1 to claim 3,

wherein switching of the turn tables to be used for polishing the wafer held at the polishing head is performed by the turn tables being moved downward and the polishing head being made to perform rotation movement.

[Claim 5]

A wafer polishing method using the polishing apparatus according to claim 2 or 3,

wherein switching of the turn tables to be used for polishing the wafer held at the polishing head is performed by the turn tables being moved downward and the polishing head being made to perform rotation movement, and

the method further comprising a step of adjusting height of the turn tables according to abrasion of the polishing pads and dressing the polishing pads after polishing of the wafer is finished.